

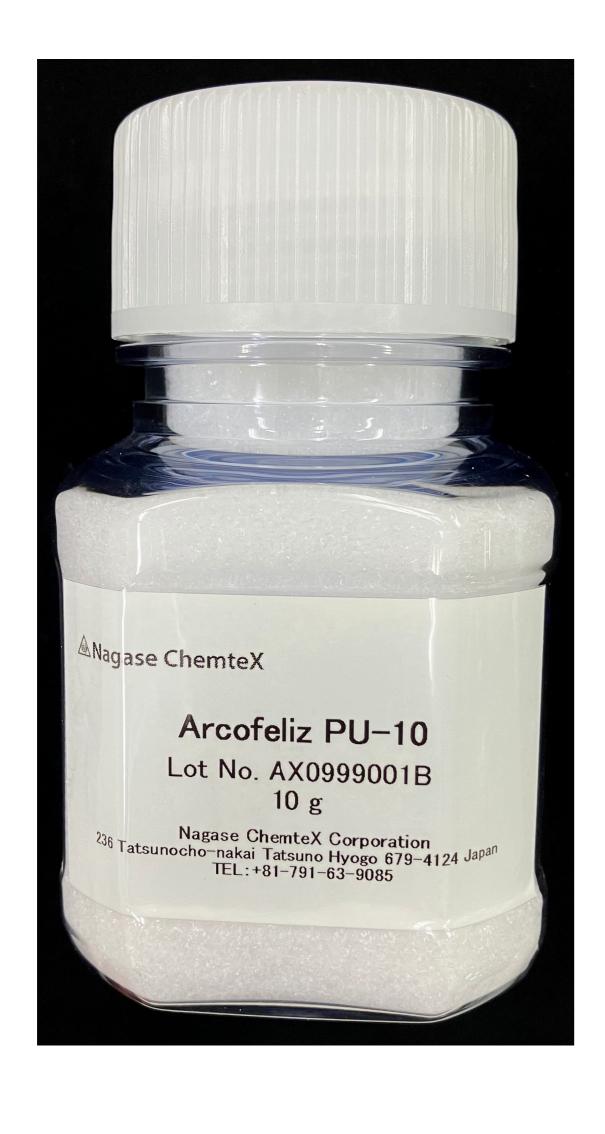
Arcofeliz PU-10

(Low-Endotoxin Pullulan)

Arcofeliz PU-10 is Low-Endotoxin Pullulan produced by purification with a newly developed endotoxin removal material*1 (non-GMP)

Developed products list

Product number	Specification	
	Japanese Pharmacopoeial	Reference
Arcofeliz PU-10	Endotoxin level	<10 EU/g
	Viable count	<100 CFU/g



Intended uses

Raw materials for implantable medical device, Regenerative medicines, Cell culture base material, Pharmaceutical raw materials

Safety test data Cytotoxicity test negative

Acute toxicity test negative

Description

This product is freeze-dried.
We can provide blocks or crushed products upon request.

*1 Collaborative research with Kumamoto University

Details of the products and download of the catalog are available via the URL or with the QR code on the right.

Advanced Endotoxin Removal Solution site https://www.nagase.co.jp/low-endotoxin/english/



Nagase & Co., Ltd. Corporate site https://www.nagase.co.jp/english/



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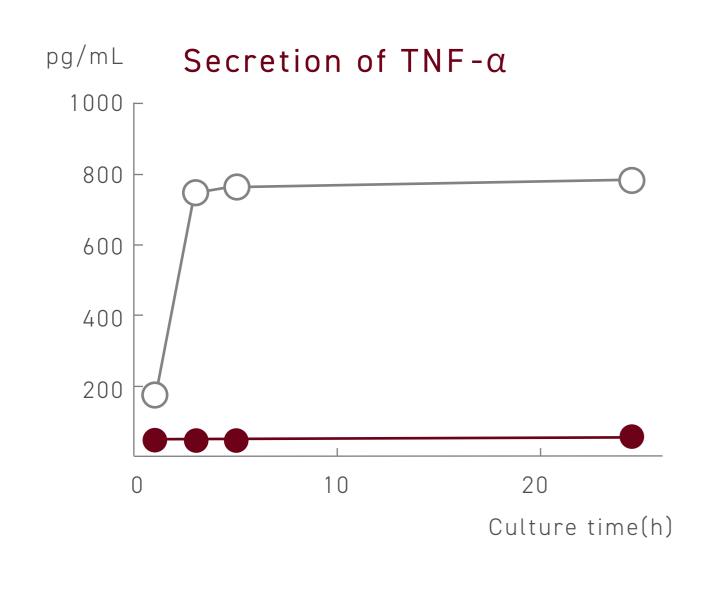


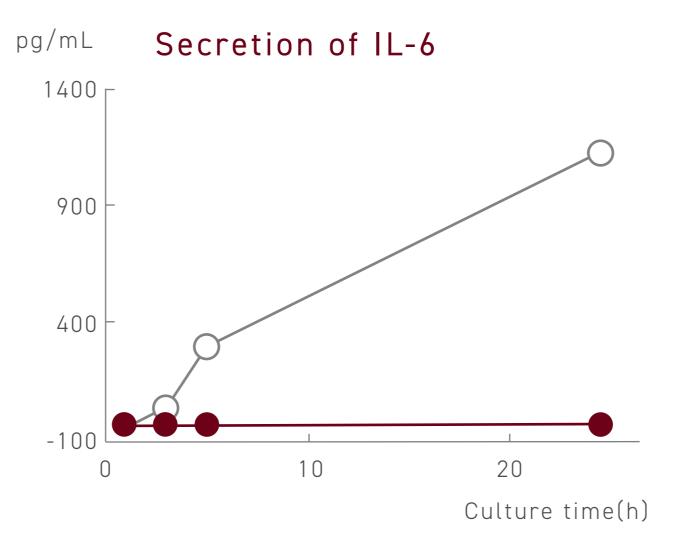


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(Low-Endotoxin Pullulan)

Biological test using macrophages *2



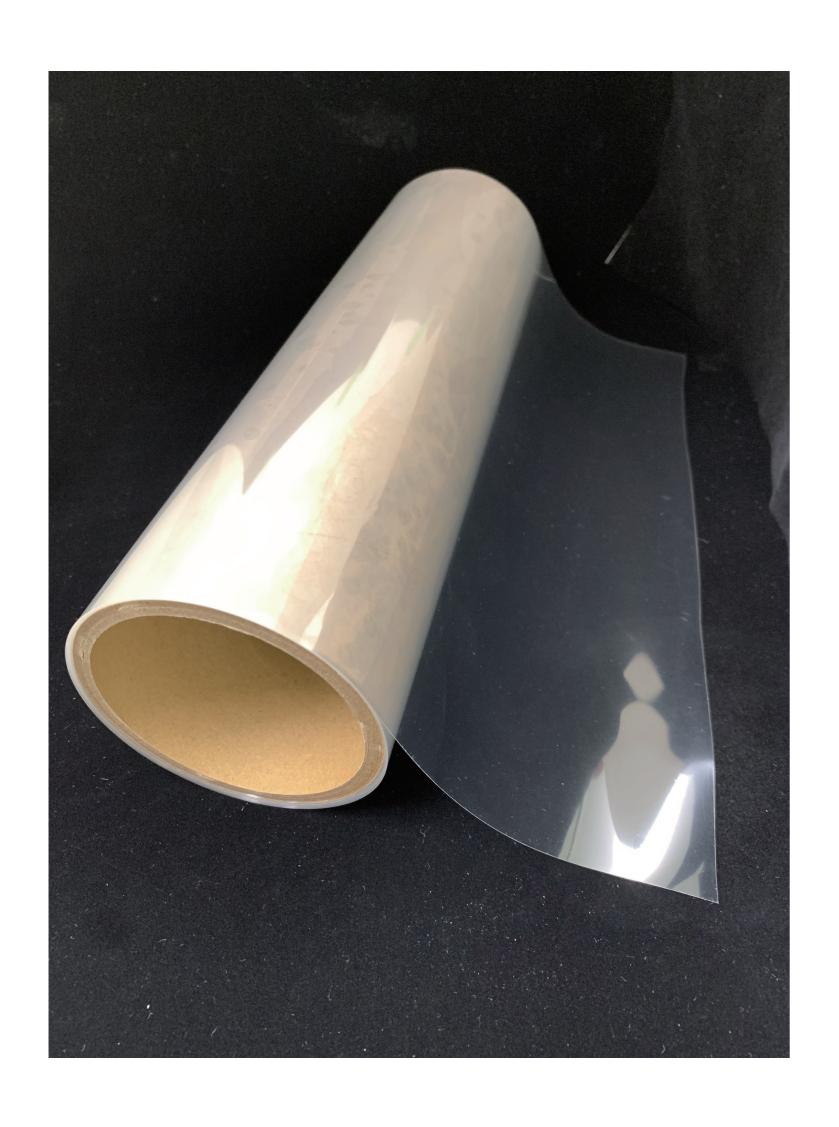


By reducing the endotoxin level, marked reduction in secretion of inflammatory cytokines (TNF- α , IL-6) was achieved.

O Japanese Pharmacopoeial Pullulan

Arcofeliz PU-10

Arcofeliz PU-10 film properties



	High strength	Low strength
Film thickness µm	30.0	30.0
Tensile modulus GPa	4.6	3.4
Tensile strength MPa	73.8	44.2
Elongation at break %	4.6	3.4
Dissolution rate s	40.0	21.5
Endotoxin level EU/g	<10.0	<10.0

Strength and dissolution rate can be adjusted by changing film forming conditions.



^{*2} Data provided by Professor Matsumura , Japan Advanced Institute of Science and Technology